



MPY100

MULTIPLIER-DIVIDER

FEATURES

- LOW COST
- DIFFERENTIAL INPUT
- ACCURACY 100% TESTED AND GUARANTEED
- NO EXTERNAL TRIMMING REQUIRED
- LOW NOISE: 90µVrms, 10Hz to 10kHz
- HIGHLY RELIABLE ONE-CHIP DESIGN
- DIP OR TO-100 TYPE PACKAGE
- WIDE TEMPERATURE OPERATION

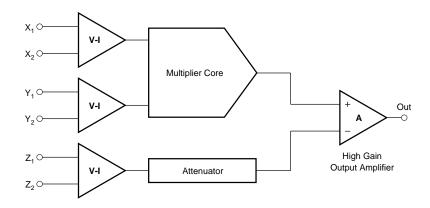
APPLICATIONS

- MULTIPLICATION
- DIVISION
- SQUARING
- SQUARE ROOT
- LINEARIZATION
- POWER COMPUTATION
- ANALOG SIGNAL PROCESSING
- ALGEBRAIC COMPUTATION
- TRUE RMS-TO-DC CONVERSION

DESCRIPTION

The MPY100 multiplier-divider is a low cost precision device designed for general purpose application. In addition to four-quadrant multiplication, it also performs analog square root and division without the bother of external amplifiers or potentiometers. Laser-trimmed one-chip design offers the most in highly

reliable operation with guaranteed accuracies. Because of the internal reference and pretrimmed accuracies the MPY100 does not have the restrictions of other low cost multipliers. It is available in both TO-100 and DIP ceramic packages.



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SPECIFICATIONS

At T_A = +25°C and $\pm V_S$ = 15VDC, unless otherwise specified.

		MPY100A		MPY100B/C			MPY100S				
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
MULTIPLIER PERFORM	I IANCE	//	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \								
Transfer Function		(^1	$\frac{(Y_1 - X_2)(Y_1 - Y_2)}{10}$			*/*			*		
			10 	l							
Total Error Initial	-10V ≤ X, Y ≤ 10V			±2.0			±1.0/0.5			±0.5	% FSR
vs Temperature	$T_{A} = +25^{\circ}C$ $-25^{\circ}C \le T_{A} \le +85^{\circ}C$		±0.017	±0.05		±0.008/0.008				±0.5	% FSR/°C
vs Temperature	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$					0.000,0.000	20.02/0.02		±0.025	±0.05	% FSR/°C
vs Supply ⁽¹⁾	Î ^		±0.05			*/*			*		% FSR/%
Individual Errors											
Output Offset Initial	T - ±25°C		±50	±100		±10/7	±50/25		±7	±50	mV
vs Temperature	$T_A = +25^{\circ}C$ $-25^{\circ}C \le T_A \le +85^{\circ}C$		±0.7	±2.0		±0.7/0.3	±2.0/±0.7		±1	130	mV/°C
vs Temperature	$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le +125^{\circ}\text{C}$								±0.3	±0.7	mV/°C
vs Supply ⁽¹⁾			±0.25			*/*			*		mV/%
Scale Factor Error											
Initial vs Temperature	$T_{A} = +25^{\circ}C$ $-25^{\circ}C \le T_{A} \le +85^{\circ}C$ $-55^{\circ}C \le T_{A} \le +125^{\circ}C$		±0.12 ±0.008			*/*			*		% FSR % FSR/°C
vs Temperature	$-25^{\circ}C \le T_A \le +05^{\circ}C$		±0.006			/			±0.008		% FSR/°C
vs Supply ⁽¹⁾	33 0 3 1 _A 3 1123 0		±0.05			*/*			*		% FSR %
Nonlinearity											
X Input	$X = 20Vp-p; Y = \pm 10VDC$		±0.08			*/*			*		% FSR
Y Input	$Y = 20Vp-p: X = \pm 10VDC$		±0.08			*/*			*		% FSR
Feedthrough X Input	f = 50Hz X = 20Vp-p; Y = 0		100			30/30			30		mVp-p
Y Input	X = 20Vp-p, Y = 0 Y = 20Vp-p; X = 0		6			*/*			*		mVp-p
vs Temperature	-25 °C $\leq T_A \leq +85$ °C		0.1			*/*					mVp-p/°C
vs Temperature	-55°C ≤ T _A ≤ 125°C								0.1		mVp-p/°C
vs Supply ⁽¹⁾			0.15			*/*			*		mVp-p/%
DIVIDER PERFORMANC	ĊE										
Transfer Function	$X_1 > X_2$		$\frac{10(Z_2 - Z_1)}{(X_1 - X_2)} +$	Υ		*/*			*		
			$(X_1 - X_2)$	1							
Total Error (with	X = 10V										
external adjustments)	-10V ≤ Z ≤ +10V		±1.5			±0.75/0.35			±0.35		% FSR
	$X = 1V$ $-1V \le Z \le +1V$		±4.0			±2.0/1.0			±1.0		% FSR
	+0.2V ≤ X ≤ +10V		14.0			12.0/1.0			11.0		/0 1 510
	-10V ≤ Z ≤ +10V		±5.0			±2.5/1.0			±1.0		% FSR
SQUARER PERFORMA	NCE										
Transfer Function	1		$\frac{(X_1 - X_2)^2}{10} +$	7		*/*			*		
			10 +	Z ₂							
Total Error	-10V ≤ X ≤ +10V		±1.2			±0.6/0.3			±0.3		% FSR
SQUARE ROOTER PER	FORMANCE										
Transfer Function	$Z_1 < Z_2$	+√	$10(Z_2 - Z_1) +$	\overline{X}_2		*/*			*		
Total Error	1V ≤ Z ≤ 10V		±2			±1/0.5			±0.5		% FSR
AC PERFORMANCE											
Small-Signal Bandwidth			550			*/*			*		kHz
% Amplitude Error	Small-Signal		70			*/*			*		kHz
% (0.57°) Vector Error	Small-Signal		5			*/*			*		kHz
Full Power Bandwidth Slew Rate	$ V_{O} = 10V, R_{L} = 2k\Omega$ $ V_{O} = 10V, R_{L} = 2k\Omega$		320 20			*/*			*		kHz V/μs
Settling Time	$\varepsilon = \pm 1\%, \ \Delta V_O = 20V$		2			*/*			*		μs
Overload Recovery	50% Output Overload		0.2			*/*			*		μs
INPUT CHARACTERIST	ics										
Input Voltage Range											
Rated Operation		±10			*/*			*			V
Absolute Maximum	X, Y, Z ⁽²⁾		10	±V _{cc}		*/*	*/*		*	_ *	V MO
Input Resistance Input Bias Current	X, Y, Z ⁽²⁾ X, Y, Z		10 1.4			*/*			*	1	MΩ μΑ
OUTPUT CHARACTERIS			····		1	<u>'</u>					
	51163 									1	
Rated Output									i		
Rated Output Voltage	$I_O = \pm 5 \text{mA}$	±10			*/*			*			V
·	$I_{O} = \pm 5\text{mA}$ $V_{O} = \pm 10V$ $f = DC$	±10 ±5	1.5		*/* */*	*/*		*			V mA Ω



SPECIFICATIONS (CONT)

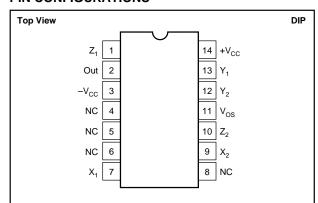
At $T_A = +25^{\circ}C$ and $\pm V_S = 15VDC$, unless otherwise specified.

			MPY100	4		MPY100B/	С		MPY100S		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
OUTPUT NOISE VOLTA	AGE X = Y = 0										
f _O = 1Hz			6.2			*/*			*		μV/√ Hz
$f_0 = 1kHz$			0.6			*/*			*		μV/√ Hz
I/f Corner Frequency			110			*/*			*		Hz
f _B = 5Hz to 10kHz			60			*/*			*		μVrms
$f_B = 5Hz$ to $5MHz$			1.3			*/*			*		mVrms
POWER SUPPLY REQU	JIREMENTS										
Rated Voltage			±15			*/*			*		VDC
Operating Range	Derated Performance	±8.5		±20	*/*		*/*	*		*	VDC
Quiescent Current			±5.5			*/*			*		mA
TEMPERATURE RANGE (Ambient)											
Specification	[`	-25		+85	*/*		*/*	-55		+125	°C
Operating Range	Derated Performance	-55		+125	*/*		*/*	*		*	°C
Storage		-65		+150	*/*		*/*	*		*	°C

^{*} Same as MPY100A specification.

NOTES: (1) Includes effects of recommended null pots. (2) Z_2 input resistance is 10M Ω , typical, with V_{OS} pin open. If V_{OS} pin is grounded or used for optional offset adjustment, the Z_2 input resistance may be as low as 25k Ω

PIN CONFIGURATIONS

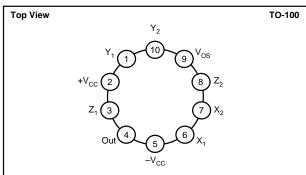


NOTES: (1) $V_{\rm OS}$ adjustment optional not normally recommended. $V_{\rm OS}$ pin may be left open or grounded. (2) All unused input pins should be grounded.

ABSOLUTE MAXIMUM RATINGS

Supply	
Internal Power Dissipation ⁽¹⁾	500mW
Differential Input Voltage ⁽²⁾	±40VDC
Input Voltage Range(2)	±20VDC
Storage Temperature Range	65°C to +150°C
Operating Temperature Range	–55°C to +125°C
Lead Temperature (soldering, 10s)	+300°C
Output Short-circuit Duration(3)	Continuous
Junction Temperature	+150°C

NOTES: (1) Package must be derated on $\theta_{JC}=15^{\circ}\text{C/W}$ and $\theta_{JA}=165^{\circ}\text{C/W}$ for the metal package and $\theta_{JC}=35^{\circ}\text{C/W}$ and $\theta_{JA}=220^{\circ}\text{C/W}$ for the ceramic package. (2) For supply voltages less than $\pm 20\text{VDC}$, the absolute maximum input voltage is equal to the supply voltage. (3) Short-circuit may be to ground only. Rating applies to +85°C ambient for the metal package and +65°C for the ceramic package.



NOTES: (1) $V_{\rm OS}$ adjustment optional not normally recommended. $V_{\rm OS}$ pin may be left open or grounded. (2) All unused input pins should be grounded.

ORDERING INFORMATION

MODEL	PACKAGE	TEMPERATURE RANGE
MPY100AG	14-Pin Ceramic DIP	-25°C to +85°C
MPY100AM	Metal TO-100	–25°C to +85°C
MPY100BG	14-Pin Ceramic DIP	−25°C to +85°C
MPY100BM	Metal TO-100	−25°C to +85°C
MPY100CG	14-Pin Ceramic DIP	−25°C to +85°C
MPY100CM	Metal TO-100	−25°C to +85°C
MPY100SG	14-Pin Ceramic DIP	-55°C to +125°C
MPY100SM	Metal TO-100	–55°C to +125°C

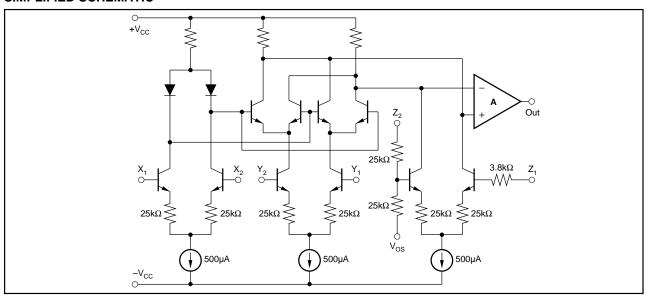
PACKAGE INFORMATION

MODEL	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
MPY100AG	14-Pin Ceramic DIP	169
MPY100AM	Metal TO-100	007
MPY100BG	14-Pin Ceramic DIP	169
MPY100BM	Metal TO-100	007
MPY100CG	14-Pin Ceramic DIP	169
MPY100CM	Metal TO-100	007
MPY100SG	14-Pin Ceramic DIP	169
MPY100SM	Metal TO-100	007

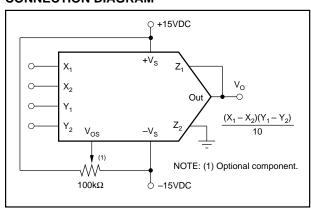
NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book.

^{*/*} B/C grades same as MPY100A specification.

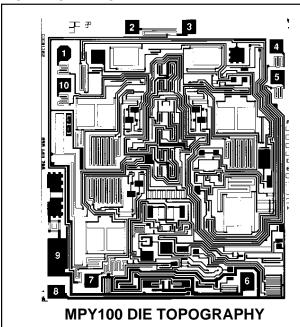
SIMPLIFIED SCHEMATIC



CONNECTION DIAGRAM



DICE INFORMATION



PAD	FUNCTION
1	Y_2
2	Y ₂ V _{OS} Z ₂ X ₂ X ₁ V _O Z ₁ +V
3	Z_2
4	X ₂
5	X ₁
6	Vo
7	Z ₁
8	+V
9	-V
10	Y ₁

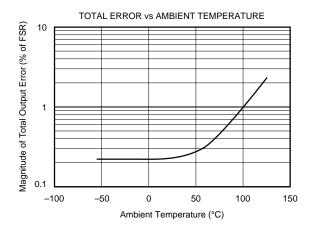
Substrate Bias: $-V_{\rm CC}$

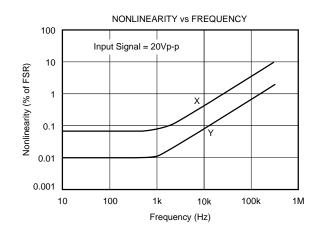
MECHANICAL INFORMATION

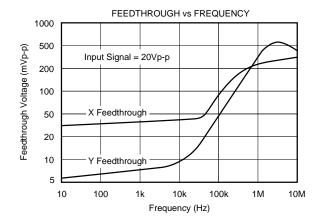
	MILS (0.001")	MILLIMETERS
Die Size	107 x 93 ±5	2.72 x 2.36 ±0.13
Die Thickness	20 ±3	0.51 ±0.08
Min. Pad Size	4 x 4	0.10 x 0.10
Backing		Gold

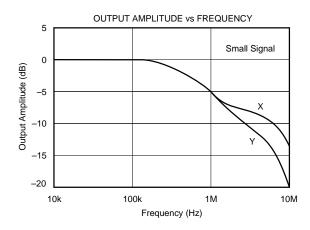
TYPICAL PERFORMANCE CURVES

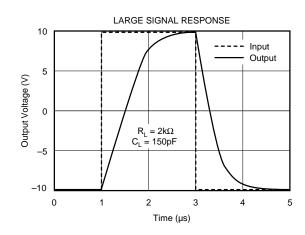
At T_A = +25°C and $\pm V_S$ = 15VDC, unless otherwise specified.

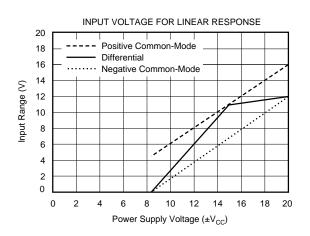








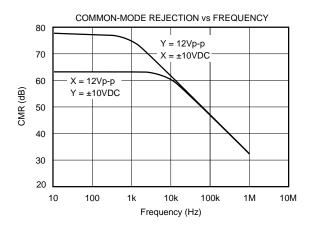


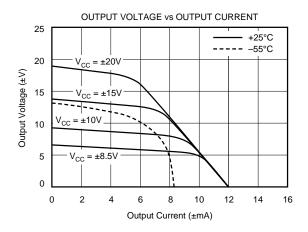


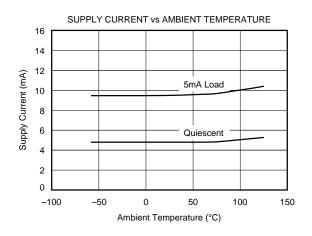
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TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C and $\pm V_S$ = 15VDC, unless otherwise specified.









THEORY OF OPERATION

The MPY100 is a variable transconductance multiplier consisting of three differential voltage-to-current converters, a multiplier core and an output differential amplifier as illustrated in Figure 1.

The basic principle of the transconductance multiplier can be demonstrated by the differential stage in Figure 2.

For small values of the input voltage, V_1 , that are much smaller than V_T , the transistor's thermal voltage, the differential output voltage, V_0 , is:

$$V_O = g_m R_L V_1$$

The transconductance g_m of the stage is given by:

$$g_m = I_E/V_T$$

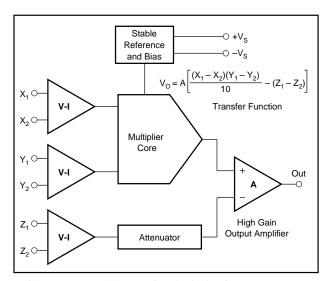


FIGURE 1. MPY100 Functional Block Diagram.

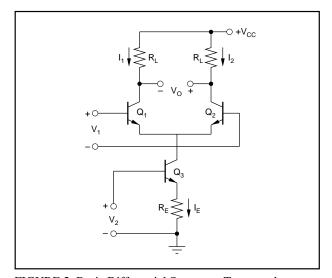


FIGURE 2. Basic Differential Stage as a Transconductance Multiplier.

and is modulated by the voltage, V2, to give

$$g_m \approx V_2/V_T R_E$$

Substituting this into the original equation yields the overall transfer function

$$V_{O} = g_{m}R_{L}V_{1} = V_{1}V_{2} (R_{L}/V_{T}R_{E})$$

which shows the output voltage to be the product of the two input voltages, V_1 and V_2 .

Variations in I_E due to V_2 cause a large common-mode voltage swing in the circuit. The errors associated with this common-mode voltage can be eliminated by using two differential stages in parallel and cross-coupling their outputs as shown in Figure 3.

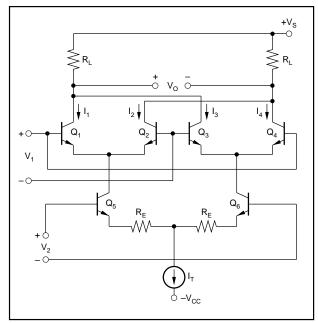


FIGURE 3. Cross-Coupled Differential Stages as a Variable-Transconductance Multiplier.

An analysis of the circuit in Figure 3 shows it to have the same overall transfer function as before:

$$V_{\rm O} = V_1 V_2 (R_{\rm L}/V_{\rm T} R_{\rm E}).$$

For input voltages larger than V_T , the voltage-to-current transfer characteristics of the differential pair $Q_1,\,Q_2$ or Q_3 and Q_4 are no longer linear. Instead, their collector currents are related to the applied voltage V_1

$$\frac{I_1}{I_2} = \frac{I_3}{I_4} = e^{\frac{V_1}{V_T}}$$

The resultant nonlinearity can be overcome by developing V_1 logarithmically to exactly cancel the exponential relationship just derived. This is done by diodes D_1 and D_2 in Figure 4.

The emitter degeneration resistors, R_X and R_Y , in Figure 4, provide a linear conversion of the input voltages to differential current, I_X and I_Y , where:



7

$$I_X = V_X/R_X$$
 and $I_Y = V_Y/R_Y$

Analysis of Figure 4 shows the voltage V_A to be:

$$V_A = (2R_L/I_1)(I_XI_Y)$$

Since I_X and I_Y are linearly related to the input voltages V_X and V_Y , V_A may also be written:

$$V_A = KV_XV_Y$$

where K is a scale factor. In the MPY100, K is chosen to be 0.1.

The addition of the Z input alters the voltage V_A to:

$$V_A = KV_XV_Y - V_Z$$

Therefore, the output of the MPY100 is:

$$V_O = A[KV_XV_Y - V_Z]$$

where A is the open-loop gain of the output amplifier. Writing this last equation in terms of the separate inputs to the MPY100 gives

$$V_{O} = A \left[\frac{(X_{1} - X_{2})(Y_{1} - Y_{2})}{10} - (Z_{1} - Z_{2}) \right]$$

the transfer function of the MPY100.

WIRING PRECAUTIONS

In order to prevent frequency instability due to lead inductance of the power supply lines, each power supply should be bypassed. This should be done by connecting a $10\mu F$ tantalum capacitor in parallel with a 1000pF ceramic capacitor from the $+V_{CC}$ and $-V_{CC}$ pins of the MPY100 to the power supply common. The connection of these capacitors should be as close to the MPY100 as practical.

CAPACITIVE LOADS

Stable operation is maintained with capacitive loads to 1000pF in all modes, except the square root mode for which 50pF is a safe upper limit. Higher capacitive loads can be driven if a 100Ω resistor is connected in series with the MPY100's output.

DEFINITIONS

TOTAL ERROR (Accuracy)

Total error is the actual departure of the multiplier output voltage form the ideal product of its input voltages. It includes the sum of the effects of input and output DC offsets, gain error and nonlinearity.

OUTPUT OFFSET

Output offset is the output voltage when both inputs V_X and V_Y are 0V.

SCALE FACTOR ERROR

Scale factor error is the difference between the actual scale factor and the ideal scale factor.

NONLINEARITY

Nonlinearity is the maximum deviation from a best straightline (curve fitting on input-output graph) expressed as a percent of peak-to-peak full scale output.

FEEDTHROUGH

Feedthrough is the signal at the output for any value of $V_{\rm X}$ or $V_{\rm Y}$ within the rated range, when the other input is zero.

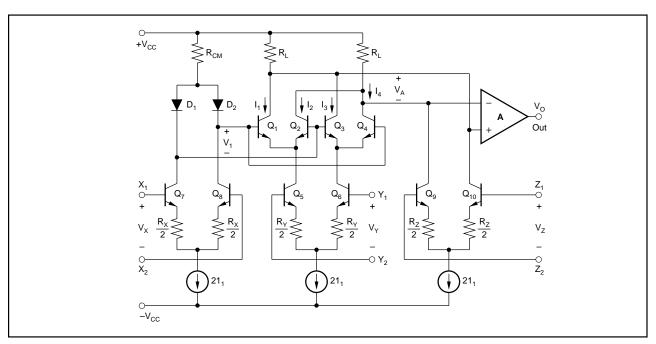


FIGURE 4. MPY100 Simplified Circuit Diagram.



SMALL SIGNAL BANDWIDTH

Small signal bandwidth is the frequency at which the output is down 3dB from its low-frequency value for nominal output amplitude of 10% of full scale.

1% AMPLITUDE ERROR

The 1% amplitude error is the frequency the output amplitude is in error by 1%, measured with an output amplitude of 10% of full scale.

1% VECTOR ERROR

The 1% vector error is the frequency at which a phase error of 0.01 radians (0.57°) occurs. This is the most sensitive measure of dynamic error of a multiplier.

TYPICAL APPLICATIONS

MULTIPLICATION

Figure 5 shows the basic connection for four-quadrant multiplication.

The MPY100 meets all of its specifications without trimming. Accuracy can, however be improved over a limited range by nulling the output offset voltage using the 100Ω optional balance potentiometer shown in Figure 5.

AC feedthrough may be reduced to a minimum by applying an external voltage to the X or Y input as shown in Figure 6

Z₂, the optional summing input, may be used to sum a voltage into the output of the MPY100. If not used, this terminal, as well as the X and Y input terminals, should be grounded. All inputs should be referenced to power supply common.

Figure 7 shows how to achieve a scale factor larger than the nominal 1/10. In this case, the scale factor is unity which makes the transfer function

$$V_{O} = KV_{X}V_{Y} = K(X_{1} - X_{2})(Y_{1} - Y_{2})K = \begin{bmatrix} \frac{1 + (R_{1}/R_{2})}{10} \end{bmatrix}$$

This circuit has the disadvantage of increasing the output offset voltage by a factor of 10, which may require the use of the optional balance control as in Figure 1 for some applications. In addition, this connection reduces the small signal bandwidth to about 50kHz.

DIVISION

Figure 8 shows the basic connection for two-quadrant division. This configuration is a multiplier-inverted analog divider, i.e., a multiplier connected in the feedback loop of an operational amplifier. In the case of the MPY100, this operational amplifier is the output amplifier shown in Figure 1.

The divider error with a multiplier-inverted analog divider is approximately:

$$\epsilon_{DIVIDER} = 10 \ \epsilon_{MULTIPLIER}/(X_1 - X_2)$$

It is obvious from this error equation that divider error becomes excessively large for small values of $X_1 - X_2$. A 10-to-1 denominator range is usually the practical limit. If more accurate division is required over a wide range of denominator voltages, an externally generated voltage may be

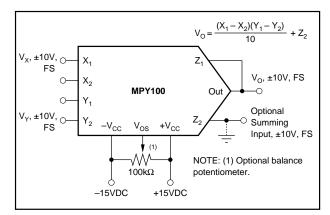


FIGURE 5. Multiplier Connection.

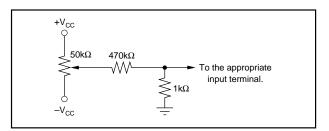


FIGURE 6. Optional Trimming Configuration.

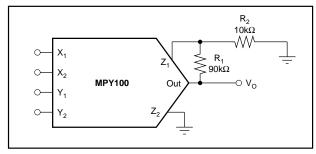


FIGURE 7. Connection for Unity Scale Factor.

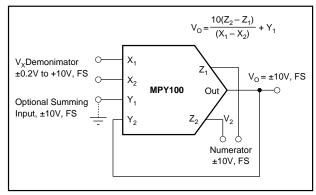


FIGURE 8. Divider Connection.



applied to the unused X-input (see Optional Trim Configuration). To trim, apply a ramp of +100 mV to +1 V at 100 Hz to both X_1 and Z_1 if X_2 is used for offset adjustment, otherwise reverse the signal polarity and adjust the trim voltage to minimize the variation in the output. An alternative to this procedure would be to use the Burr-Brown DIV100, a precision log-antilog divider.

SQUARING

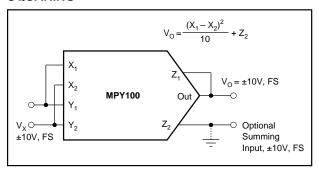


FIGURE 9. Squarer Connection.

SQUARE ROOT

Figure 10 shows the connection for taking the square root of the voltage V_Z . The diode prevents a latching condition which could occur if the input momentarily changed polarity. This latching condition is not a design flaw in the MPY100, but occurs when a multiplier is connected in the feedback loop of an operational amplifier to perform square root functions.

The load resistance, $R_{L,}$ must be in the range of $10k\Omega \le R_L \le 1M\Omega$. This resistance must be in the circuit as it provides the current necessary to operate the diode.

PERCENTAGE COMPUTATION

The circuit of Figure 11 has a sensitivity of 1V/% and is capable of measuring 10% deviations. Wider deviation can be measured by decreasing the ratio of R_2/R_1 .

BRIDGE LINEARIZATION

The use of the MPY100 to linearize the output from a bridge circuit makes the output $V_{\rm O}$ independent of the bridge supply voltage. See Figure 12.

TRUE RMS-TO-DC CONVERSION

The rms-to-DC conversion circuit of Figure 13 gives greater accuracy and bandwidth but with less dynamic range than most rms-to-DC converters.

SINE FUNCTION GENERATOR

The circuit in Figure 14 uses implicit feedback to implement the following sine function approximation:

$$V_O = (1.5715V_1 - 0.004317V_1^3)/(1 + 0.001398V_1^2)$$

= 10 sin (9V₁)

MPY100

MORE CIRCUITS

The theory and procedures for developing virtually any function generator or linearization circuit can be found in the Burr-Brown/McGraw Hill book "FUNCTION CIRCUITS - Design and Applications."

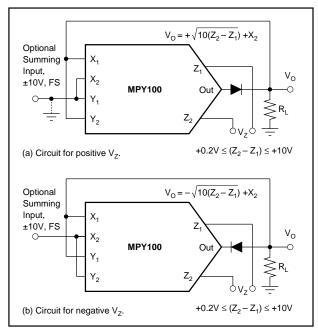


FIGURE 10. Square Root Connection.

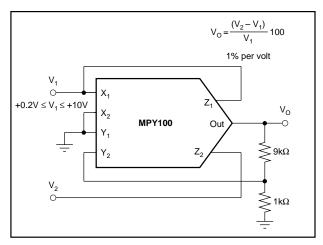


FIGURE 11. Percentage Computation.

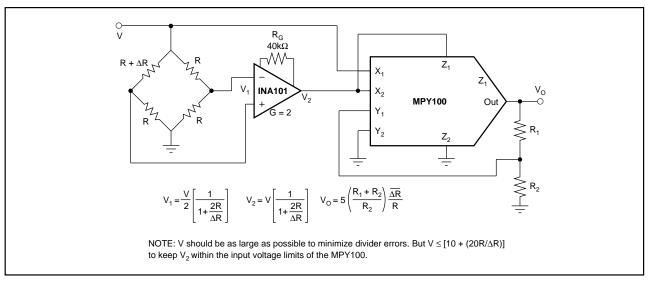


FIGURE 12. Bridge Linearization.

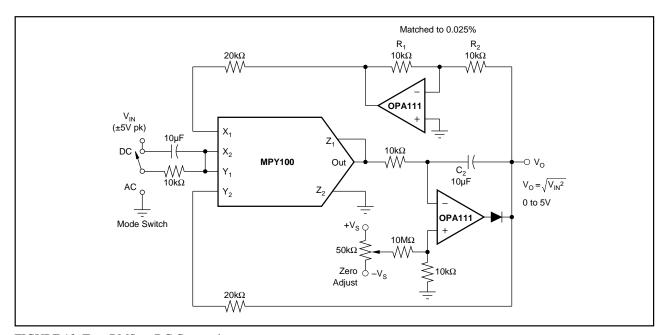


FIGURE 13. True RMS-to-DC Conversion.

11

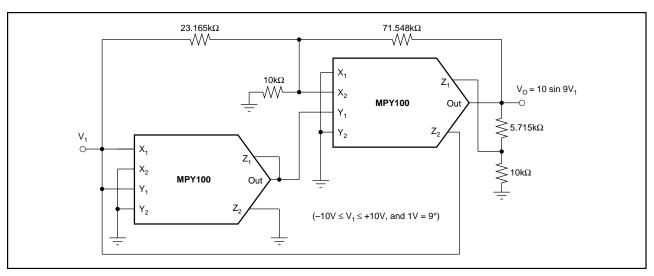


FIGURE 14. Sine Function Generator

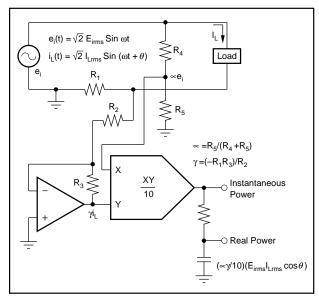


FIGURE 15. Single-Phase Instantaneous and Real Power Measurement.

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MPY100AG3	OBSOLETE	CDIP SB	JD	14		TBD	Call TI	Call TI
MPY100AM	OBSOLETE	TO-100	LME	10		TBD	Call TI	Call TI
MPY100BG	NRND	CDIP SB	JD	14	24	Green (RoHS & no Sb/Br)	Call TI	N / A for Pkg Type
MPY100BG2	OBSOLETE	CDIP SB	JD	14		TBD	Call TI	Call TI
MPY100BM	OBSOLETE	TO-100	LME	10		TBD	Call TI	Call TI
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MPY100SG	NRND	CDIP SB	JD	14	27	Green (RoHS & no Sb/Br)	Call TI	N / A for Pkg Type
MPY100SM	OBSOLETE	TO-100	LME	10		TBD	Call TI	Call TI

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